

PATENT NUMBER

U.S. **UTILITY** Patent Application

SA SCANNED <u>SBI</u> O.A. <u>LR</u>	PATENT DATE
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APPLICATION NO. 09/893198	CONT/PRIOR	CLASS 438	SUBCLASS 586	ART UNIT 28.12	EXAMINER Bous
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APPLICANTS

Ramkumar Subramanian
Michael Templeton
Bhanwar Singh
Bharath Rangarajan

2818

TITLE

Growing copper vias or lines within a patterned resist using a copper seed layer

PTO-2040
1-79

ISSUING CLASSIFICATION												
ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)		NOTICE OF ALLOWANCE MAILED 	
	_____ (Primary Examiner) (Date)			
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ 			ISSUE FEE	
	_____ (Amount Due)	_____ (Date Paid)		
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)		ISSUE BATCH NUMBER	
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